

Photos depicting the *Bluetooth Low Energy* and *802.15.4* wireless radio module with model name of <u>BGM240S22A</u>

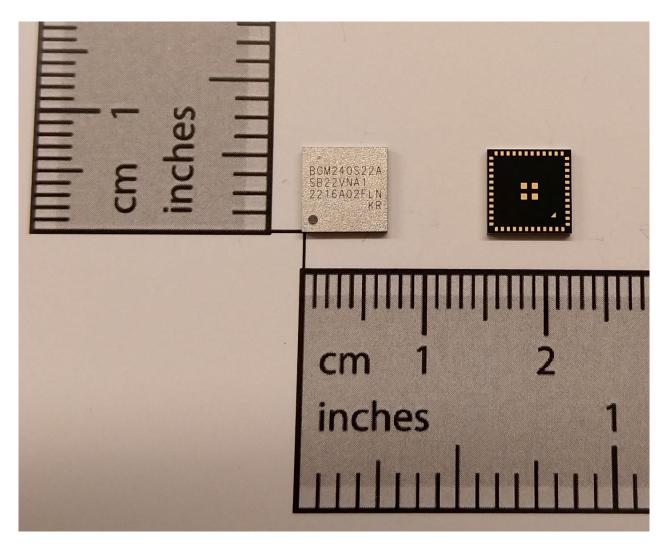


Figure 1: Left: Top/Front External view – Right: Bottom/Rear External View

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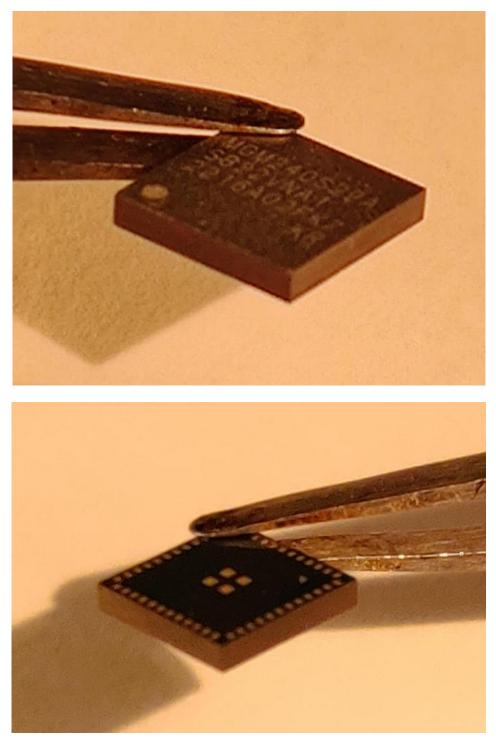


Figure 2 and 3: Details of module's packaging (*)

(*) It shows in particular that all internal components are not accessible because they are enclosed by the molding material which fills all empty spaces (just like any other IC). Integrators and users do not have access to the internals of the module, due to the fact that the module is completely molded and mechanically removing the molding material will destroy the module and break the parts in it.

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